

REMARKS

The Examiner is thanked for the thorough examination and search of the subject.

Claims 219-267 have been newly added. Claims 1-218 have been canceled.

Some or all of newly-added claims are believed to be in condition for Allowance, and that is so requested.

Applicants have amended the Specification to improve the Title, and to provide information on related patents and patent applications.

In regards to the Title, Applicants have amended the Title to "CHIP PACKAGE WITH DIE AND SUBSTRATE" to limit the focus to the claimed invention. Applicants respectfully request that this title be entered by amendment.

In regards to the related patents and patent applications, Applicant has provided information on related patents and patent applications relevant to the present application.

Response to Election/Restrictions

In claim 219, the limitation of "a patterned line over said only one preformed die and over said preformed substrate" is added. Due to the added limitation, claim 219 should be deemed within the invention scope of "a patterned line was formed over the substrate", which is requested by Examiner.

Response to Claims

Reconsideration of Claim 164 rejected under 35 USC 112, second paragraph, in the office action mailed Feb. 17, 2005, as being indefinite for failing to particularly point out and distinctly claim the subject matter which applicant regards as the invention is requested based on the Canceled Claim 164 and on the following remarks.

The cancellation of Claim 164 makes the grounds for this rejection moot. Applicant believes that New Claims 219-267 are distinct in claiming the subject matter which Applicant regards as the invention.

Reconsideration of Claims 143-145, 148-151, 156, 157, 160-162, 164-167 rejected under 35 USC 102(e) in the office action mailed Feb. 17, 2005, as being anticipated by Maruyama (US2001/0042901) is requested based on the Canceled Claims 143-145, 148-151, 156, 157, 160-162, 164-167 and on the following remarks.

The cancellations of Claims 143-145, 148-151, 156, 157, 160-162, 164-167 makes the grounds for this rejection moot. Applicant believes that New Claims 219-267 are distinct in claiming the subject matter which Applicant regards as the invention.

Reconsideration of Claims 143 and 163 rejected under 35 USC 102(e) in the office action mailed Feb. 17, 2005, as being anticipated by Hozoji (US2002/0079575) is requested based on the Canceled Claims 143 and 163 and on the following remarks.

The cancellations of Claims 143 and 163 makes the grounds for this rejection moot. Applicant believes that New Claims 219-267 are distinct in claiming the subject matter which Applicant regards as the invention.

Reconsideration of Claims 146-147 rejected under 35 USC 103(a) in the office action mailed Feb. 17, 2005, as being unpatentable over Maruyama (US2001/0042901) as applied to claim 143 and further in combination with Gonzolez (US2003/0080437) is requested based on the Canceled Claims 146-147 and on the following remarks.

The cancellations of Claims 146-147 makes the grounds for this rejection moot. Applicant believes that New Claims 219-267 are distinct in claiming the subject matter which Applicant regards as the invention.

Reconsideration of Claims 152-155 rejected under 35 USC 103(a) in the office action mailed Feb. 17, 2005, as being unpatentable over Maruyama (US2001/0042901) as applied to claim 143 and further in combination with Sakaf et al. (US2001/0033474) is requested based on the Canceled Claims 152-155 and on the following remarks.

The cancellations of Claims 152-155 makes the grounds for this rejection moot. Applicant believes that New Claims 219-267 are distinct in claiming the subject matter which Applicant regards as the invention.

In Claims 219-267

As newly added, independent claim 219 is recited below:

219. A chip package comprising:
a preformed substrate comprising semiconductor material, said preformed substrate having no circuitry;
only one preformed die joined with said preformed substrate; and
a patterned line over said only one preformed die and over said preformed substrate.

Applicants respectfully assert that the chip package claimed in claim 168 patentably distinguishes over the citations by Maruyama and by Hozoji.

Maruyama (US2001/0042901) teaches a semiconductor wafer 11 provided with multiple circuit regions 12. ~ See FIGS. 17A-17D and paragraph [0083] ~ Maruyama fails to teach the circuit regions 12 can be preformed. Applicants teach a die can be preformed and the preformed

die can be joined with a preformed substrate comprising semiconductor material, which is not taught by Maruyama.

Hozoji (US2002/0079575) teaches a preformed die 1 can be joined with a preformed substrate having multiple circuit layers 8 and 31. ~ See FIG. 7 ~ Hozoji fails to teach the preformed die 1 can be joined with a preformed substrate having no circuitry. Applicants teach a preformed die can be joined with a preformed substrate having no circuitry, which is not taught by Hozoji.

For at least the foregoing reasons, applicants respectfully submit independent claim 219 patently defines over the prior art references, and should be allowed. For at least the same reasons, dependent claims 220-267 patently define over the prior art as well.

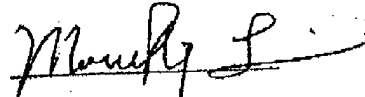
Based on the above mentioned, applicants believe that the reply is fully responsive to the Office Action mailed Feb. 18, 2005.

CONCLUSION

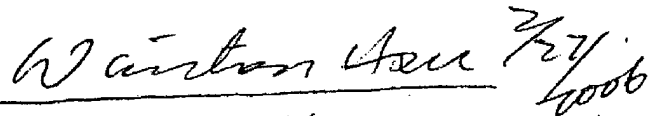
For at least the foregoing reasons, it is believed that the pending claims 219-269 are in proper condition for allowance.

Date: October 19, 2005

Respectfully submitted,



Mou-Shiung Lin, CEO
For and on behalf of MEGIC
Corporation



WINSTON HSU

REG. NO. 41526